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(54) **Title:** PACKAGED INTEGRATED CIRCUIT DEVICES WITH THROUGH- BODY CONDUCTIVE VIAS, AND METHODS OF MAKING SAME

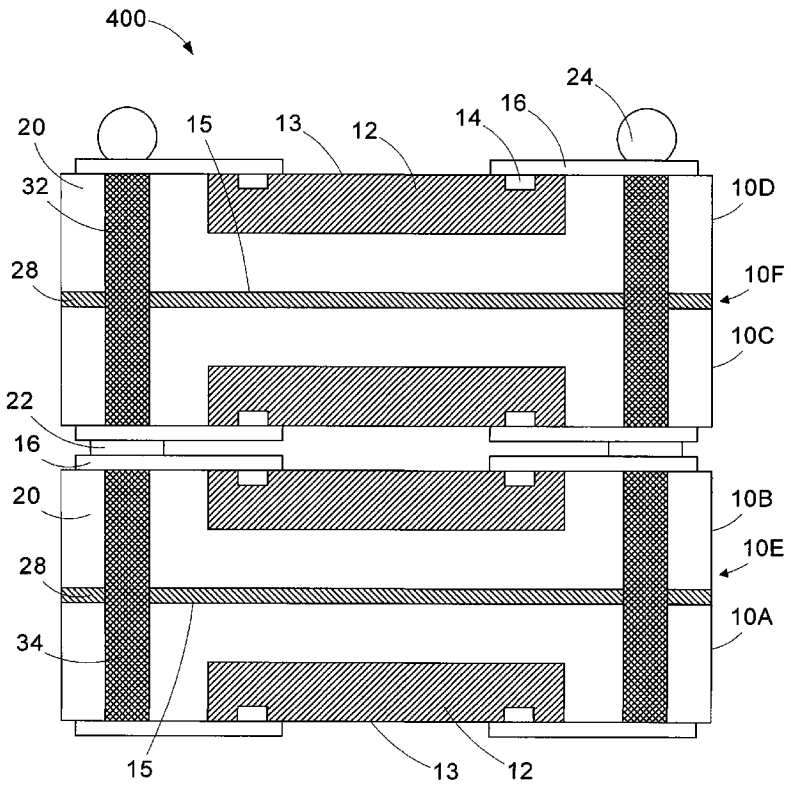


Figure 4

(57) **Abstract:** A device (400) is disclosed which includes at least one integrated circuit die (12), at least a portion of which is positioned in a body of encapsulant material (20), and at least one conductive via (32,34) extending through the body of encapsulant material.

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